Plastic Packages for Integrated Circuits

Package Outline Drawing
W5x7.28
28 BALL WAFFER LEVEL CHIP SCALE PACKAGE (WLCSP)
Rev 0, 7/12

NOTES:
2. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Bump position designation per JESD 95-1, SPP-010.